

ABSTRACT

To provide a semiconductor device with increased reliability between a mounting substrate and sealing resin and a method of manufacturing the same. The semiconductor device includes a mounting substrate including a step portion in the periphery; first and second conductive patterns formed on the front and back surfaces of the mounting substrate, respectively; a semiconductor element fixed to the mounting substrate and electrically connected to the first conductive patterns; and sealing resin covering the front surface of the mounting substrate and the step portion and seals the semiconductor element.